

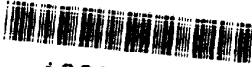
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Patent and Trademark Office



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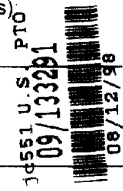
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To the Honorable Commissioner of Patents and Trademarks: Please record attached original documents or copy thereof

WRD 8-12-98

1. Name of Conveying Part(ies):  
Tongbi Jiang  
David Y. Kao  
  
Additional name(s) of conveying party(ies) attached?  Yes:  No

2. Name and address of receiving party(ies):  
Name: Micron Technology, Inc.  
Internal Address:  
  
Street Address: 8000 South Federal Way  
  
City: Boise State: ID Zip: 83706-9632  
  
Additional names(s) & address(es) attached:  Yes  No



3. Nature of conveyance:  
 Assignment  Security Agreement  
 Merger  Change of Name  
 Other \_\_\_\_\_  
  
Execution Date: July 31, 1998

4. Application number(s) or patent number(s):  
If this document is being filed together with a new application, the execution date of the application is: July 31, 1998  
  
A. Patent Application No(s):  
09/133297  
Additional numbers attached:  Yes  No  
  
B. Patent No(s):  
Additional numbers attached:  Yes  No

09/13/98  
04 10:58

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: David G. Latwesen, Ph.D.  
  
Internal Address:  
Wells, St. John, Roberts,  
Gregory & Matkin P.S.  
  
Street Address: 601 W. First Avenue, Ste. 1300  
  
City: Spokane State: WA Zip: 99201-3828

6. Total number of applications and patents involved: 1  
  
7. Total fee (37 CFR 3.41): \$40.00  
 Enclosed  
 Authorized to be charged to deposit account  
  
8. Deposit account number: 23-0925  
  
(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and Signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*  
  
David G. Latwesen, Ph.D. \_\_\_\_\_  
Name of Person Signing Signature Date  
  
TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT: 5

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PATENT  
REEL: 9397 FRAME: 0381

1 **ASSIGNMENT**

2 **PARTIES TO THE ASSIGNMENT:**

3 **INVENTORS:**

4 Tongbi Jiang

5 David Y. Kao

6 **ASSIGNEE:**

7 Micron Technology, Inc.  
8 Corporation of the State of Delaware  
9 8000 South Federal Way  
Boise, Idaho 83706-9632

10 **BACKGROUND OF THIS ASSIGNMENT:**

11 INVENTORS have conceived certain new and useful inventions  
12 disclosed in a United States patent application titled "Semiconductor  
13 Processing Methods."

14 MICRON TECHNOLOGY NC. desires to acquire the entire right,  
15 title and interest in said inventions and with respect to any Letters  
16 Patent that may be granted with respect to the inventions in both the  
17 United States and in all foreign countries.

18 **THE PARTIES AGREE AS FOLLOWS:**

19 In consideration of good and valuable consideration, the receipt  
20 sufficiency and adequacy of which is hereby acknowledged, INVENTORS  
21 hereby sell, assign and transfer to MICRON TECHNOLOGY, INC. the  
22 entire right, title and interest in the above-identified application executed  
23 currently with this assignment and to any reissues, renewals, divisions or  
24 continuations thereof, and hereby authorizes the Commissioner of Patents

1 and Trademarks to issue such Letters Patent to MICRON  
2 TECHNOLOGY, INC., for the sole use of MICRON TECHNOLOGY,  
3 INC., its successors or assigns.

4 INVENTORS further agree to execute, at the request and expense  
5 of MICRON TECHNOLOGY, INC. such other formal documents as may  
6 be required to fully convey the interest transferred herein and will  
7 similarly execute any application papers required for the filing of any  
8 division, continuation, renewal or reissue of the patent application or  
9 resulting Letters Patent; and will generally do everything necessary or  
10 desirable to obtain and enforce proper protection for the inventions  
11 assigned hereby.

12 INVENTORS further assign to MICRON TECHNOLOGY, INC. the  
13 whole right, title and interest in the inventions disclosed in the  
14 application throughout all countries foreign to the United States.  
15 MICRON TECHNOLOGY, INC. is hereby authorized to apply for  
16 patents relating to the inventions in its own name in countries where  
17 such procedure is proper; to claim the benefit of the International  
18 Convention; to file and prosecute International Applications relating to  
19 the inventions under the Patent Cooperation Treaty; and to file and  
20 prosecute applications relating to the inventions under the European  
21 Patent Convention. INVENTORS agree to execute applications relating  
22 to the inventions in those countries and under those conventions where  
23 it is necessary that the same be executed by the inventor, and to  
24 execute assignments of such applications and the resulting Letters Patent

1 to MICRON TECHNOLOGY, INC. as well as all other necessary papers  
2 in relation to such applications and Letters Patent.

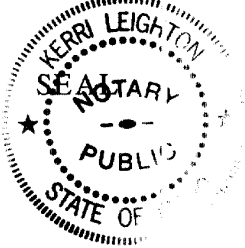
3 INVENTORS further warrant and covenant that no assignment,  
4 grant, mortgage, license or other agreement affecting the rights and  
5 property herein conveyed has been or will be made to others by the  
6 undersigned, and that the full rights to convey the same as herein  
7 expressed is possessed by the undersigned.

8 To be binding on the heirs, assigns, representatives and successors  
9 of the undersigned and extend to the successors, assigns and nominees  
10 of the Assignees.

11 (Signature) Tongbi Jiang Date: 7/31/98  
12 Tongbi Jiang

13 State of IDAHO )  
14 : ss.  
15 County of Ada )

16 BEFORE ME, this 31 day of JULY 1998,  
17 personally appeared the above-named inventor, to me known to be the  
18 person who is described in and who executed the foregoing assignment  
19 instrument and acknowledged to me that he/she executed the same of  
20 his/her own free will for the purpose therein expressed.



21 Kerri Leighton  
22 Notary or Consular Officer  
23 My Commission Expires: 1/9/2002  
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(Signature)

*David Y. Kao*  
David Y. Kao

Date:

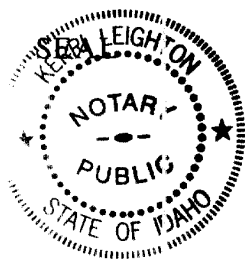
7/31/98

State of IDAHO )

: ss.

County of Ada )

BEFORE ME, this 31 day of JULY 1998,  
personally appeared the above-named inventor, to me known to be the  
person who is described in and who executed the foregoing assignment  
instrument and acknowledged to me that he/she executed the same of  
his/her own free will for the purpose therein expressed.



*Vera Leighton*  
Notary or Consular Officer  
My Commission Expires: 1/9/2002